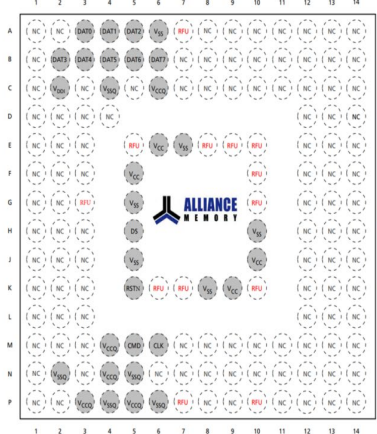
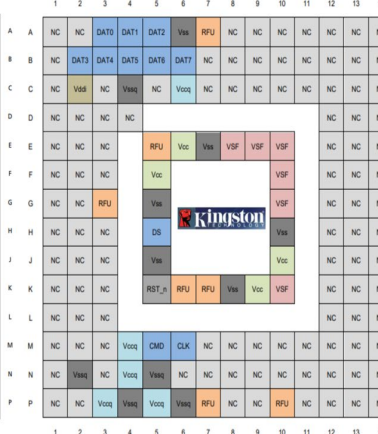


ASFC8G31M-51BIN vs EMMC08G-ML36-0xx00 Comparison

Part Number & result Parameter	ASFC8G31M-51BIN	EMMC08G-ML36-0xx00	Comparison Result
Product Description	eMMC	eMMC	Same
Capacity	8GB	8GB	Same
Bus Width	x1, x4 & x8	x1, x4 & x8	Same
eMMC Version	5.1 (backward compatible with previous MMC)	5.1 (backward compatible with previous MMC)	Same
Operating Power Supply (Interface)	VccQ = 1.70V ~ 1.95V or 2.7V ~ 3.6V	VccQ = 1.70V ~ 1.95V or 2.7V ~ 3.6V	Same
Operating Power Supply (NAND)	Vcc = 2.7V~3.6V	Vcc = 2.7V~3.6V	Same
Operating Temperature	Industrial (Ta = -40°C ~ 85°C)	Industrial (Ta = -25°C ~ 85°C)	Alliance better
Clock Frequency	MMC I/F Clock: 0~200MHz (Max) MMC I/F Boot Freq: 0~52MHz	MMC I/F Clock: 0~200MHz (Max) MMC I/F Boot Freq: 0~52MHz	Same
Interface Timing Mode	HS200/ HS400	HS200/ HS400	Same
NAND Flash Component	Type: MLC Density: 64Gb Die:1	Type: MLC Density: 64Gb Die:1	Same
Sequential Performance (HS400)	Write: 80MB/s Read = 140MB/s	Write: 20MB/s Read = 115MB/s	Alliance better
Package Type	153-ball TFBGA 11.5 x 13mm	153-ball TFBGA 11.5 x 13mm	Same
Package Material	Pb and Halogen Free	Pb and Halogen Free	Same
Pin to Pin Compatible	ASFC8G31M-51BIN  EMMC08G-ML36-01B00 		Same